

Prepn. of laminated fluorine-contg. resin board - by impregnating textile substrate with fluorine contg. resin dispersion and with fluorine contg. resin dispersion contg. micropowdery inorganic filler, etc.

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Abstract (Basic): JP 4125140 A

Laminated F-contg. resin board is prepd. by impregnating a textile substrate with F-contg. resin dispersion and then with F-contg. resin dispersion contg. micropowder inorganic filler to provide prepreg. laminating prepreg sheets, laminating the surfaces with metal foil(s) and integrating the laminated sheets.

Aq. dispersion of F-contg. resin is pref. of PTFE of particle size of about 0.2 microns and a specific gravity of 2.1 and a consistency of 50-60%. Metal foil is pref. Al or Cu. Inorganic filler is pref. fused SiO₂ powder having a dielectric constant of 3.5, a specific gravity of 2.2, an average particle size of 3 microns and a thermal expansion coefft. of $4 \times 10^{\text{power}(-6)} / \text{deg.C}$ and is used in an amt. of 10-100 vol.% per 100 vol. pts. F-contg. resin. Textile substrate is pref. woven glass fibre. Impregnation of F-contg. dispersions is each carried out up to 4 passes.

USE/ADVANTAGE - Used as printed circuit boards. Laminated board has improved insulating resistance after the moisture absorption is $10^{\text{power}(13)}$ ohms, improved thermal expansion, drilling workability and electrical properties.

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Title Terms: PREPARATION; LAMINATE; FLUORINE; CONTAIN; RESIN; BOARD; IMPREGNATE; TEXTILE; SUBSTRATE; FLUORINE; CONTAIN; RESIN; DISPERSE; FLUORINE; CONTAIN; RESIN; DISPERSE; CONTAIN; INORGANIC; FILL

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